

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): TANAKA et al

Serial No.: 09/942,213

Filed: August 30, 2001

For: Method And Apparatus For Inspecting A Semiconductor Device

Group: 2812

Examiner:



PROPOSED AMENDMENTS TO THE DRAWINGS

Assistant Commissioner for Patents
Washington, DC 20231

December 27, 2001

Sir:

It is proposed that the drawings in the above-identified application be amended in accordance with the attached red-lined prints, and approval of these drawing corrections is respectfully requested at this time.

Upon receipt of the approval of the amendments to the drawings and receipt of the official Notice of Allowance, the drawing amendments will be effected.

Respectfully submitted,

ANTONELLI, TERRY, STOUT & KRAUS, LLP

A handwritten signature in black ink, appearing to read "Alan E. Schiavelli". The signature is fluid and extends horizontally across the page.

Alan E. Schiavelli
Registration No. 32,087

DRA/AES/jla
(703) 312-6600
Attachments



FIG. 5(a)

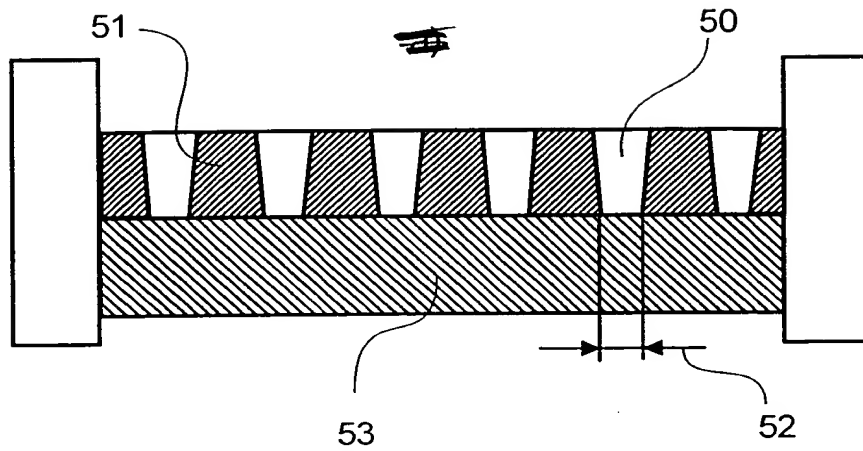


FIG. 5(b)

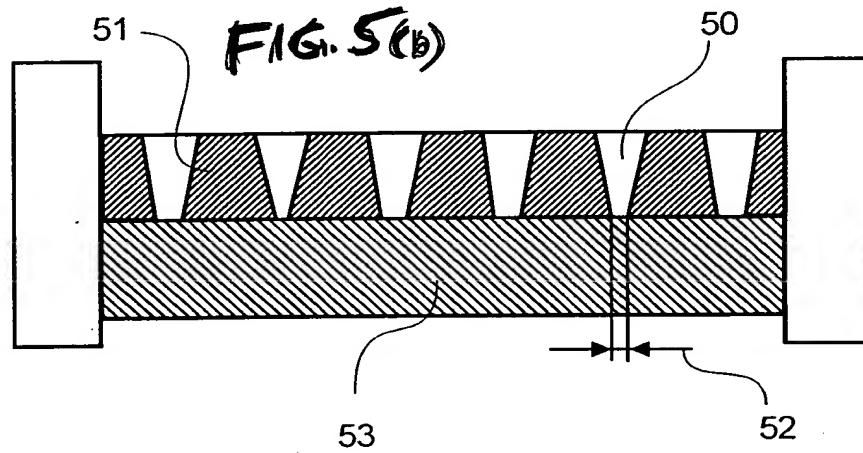


FIG. 5(c)

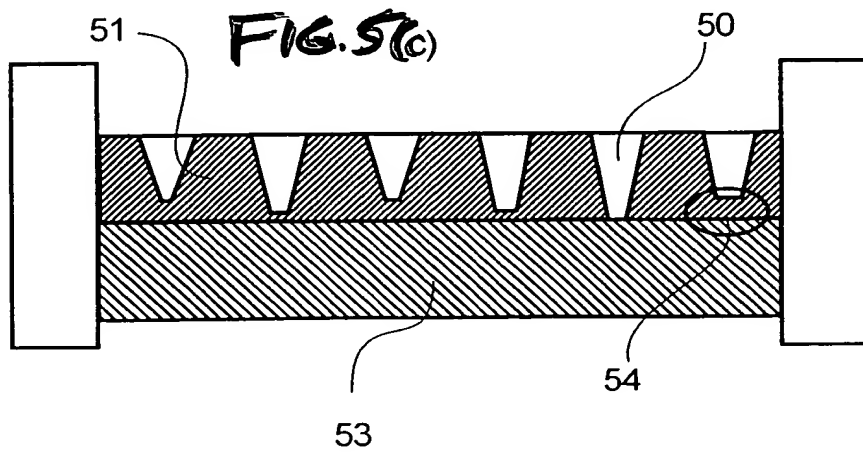


FIG. 6

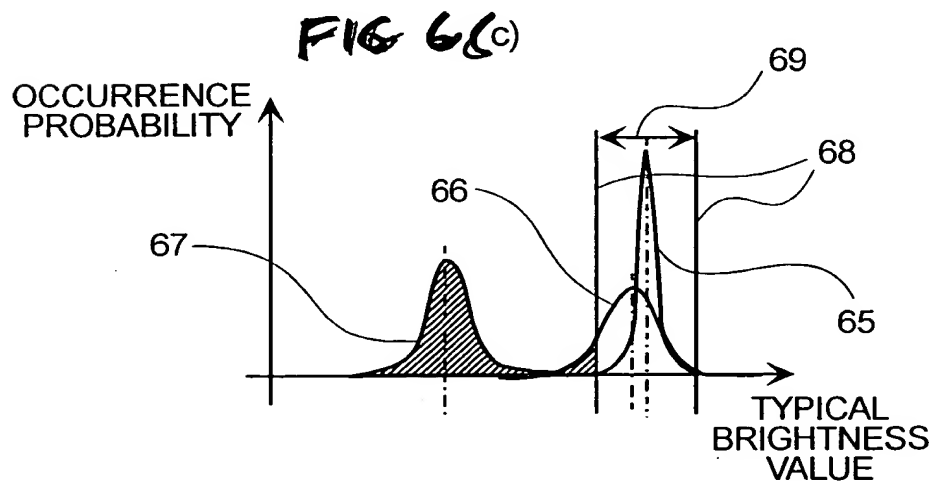
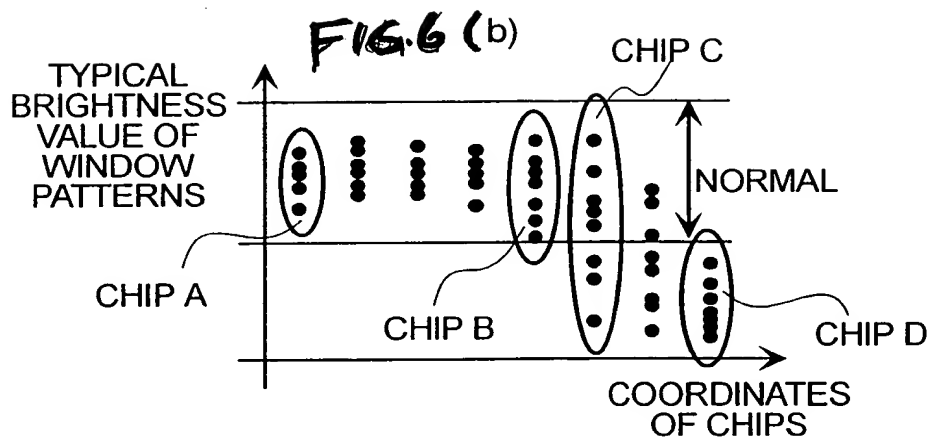
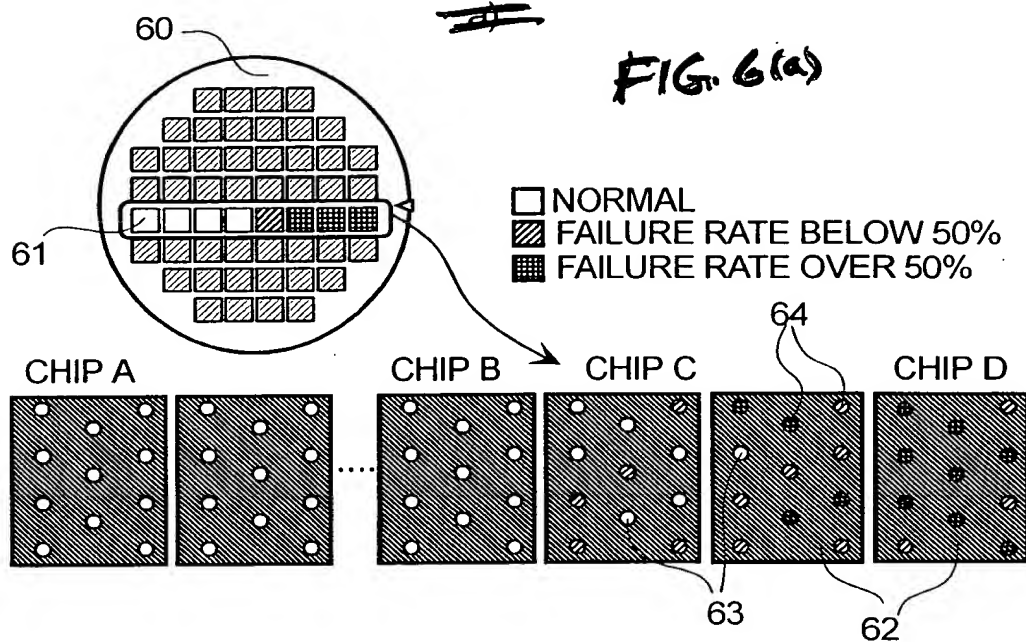


FIG. 8 (a)

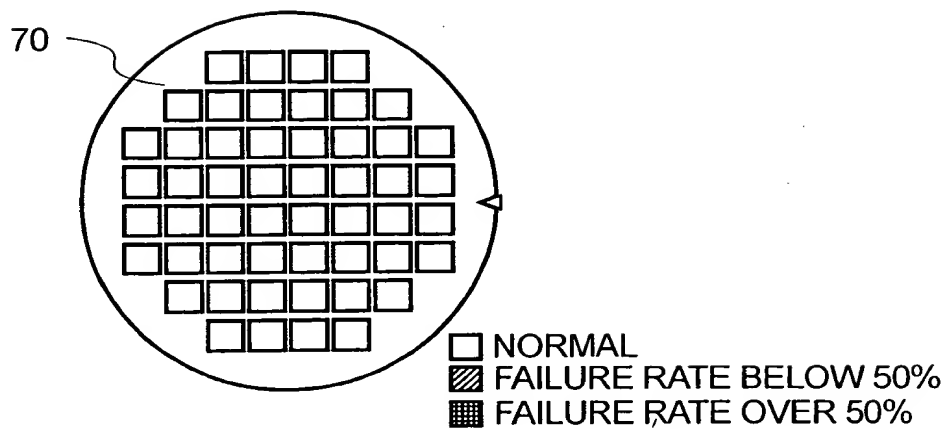


FIG. 8(b)

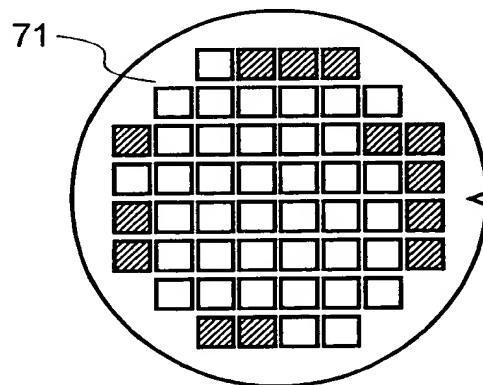


FIG. 8(c)

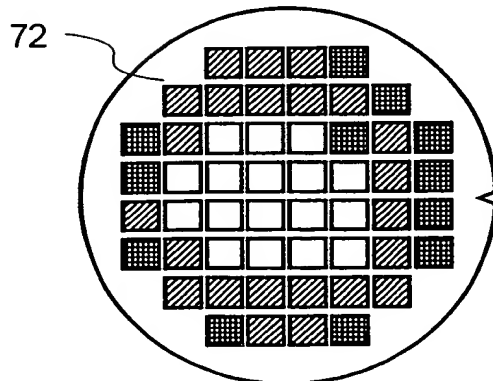




FIG. 9(a)

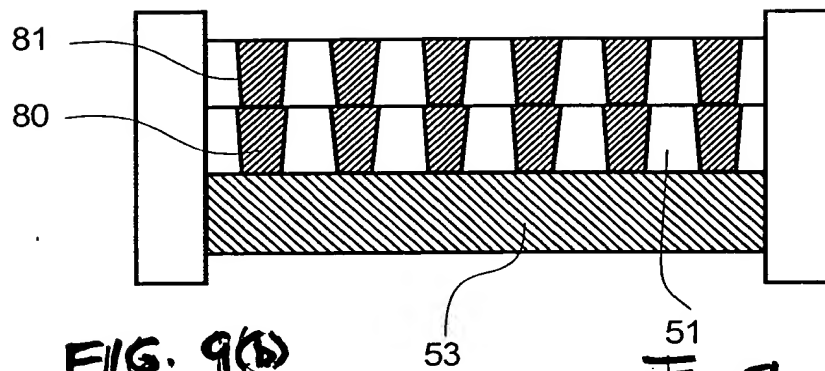


FIG. 9(b)

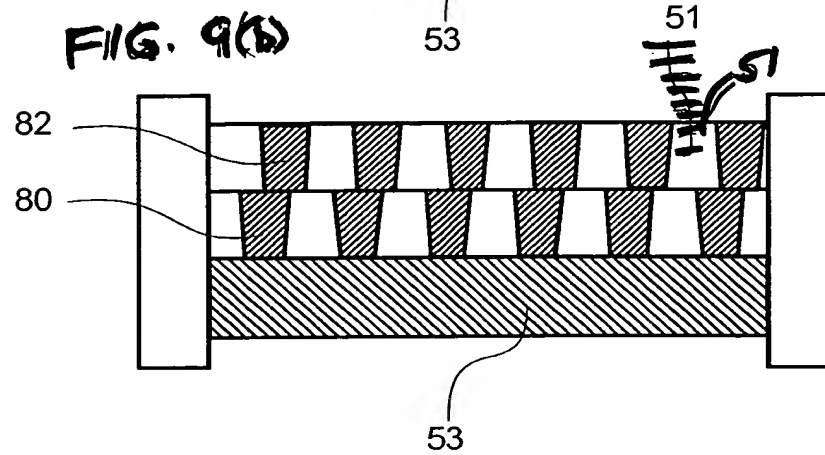




FIG.10(a)

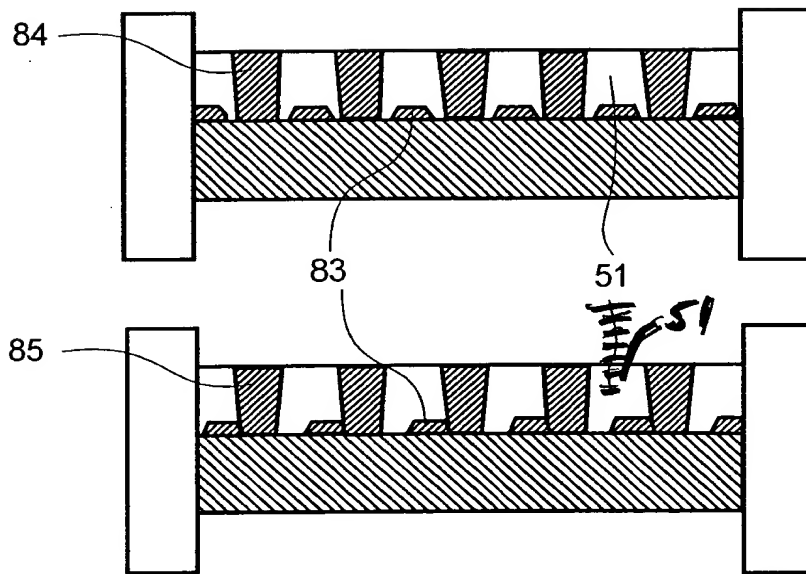


FIG. 10(b)

FIG.12 (a)

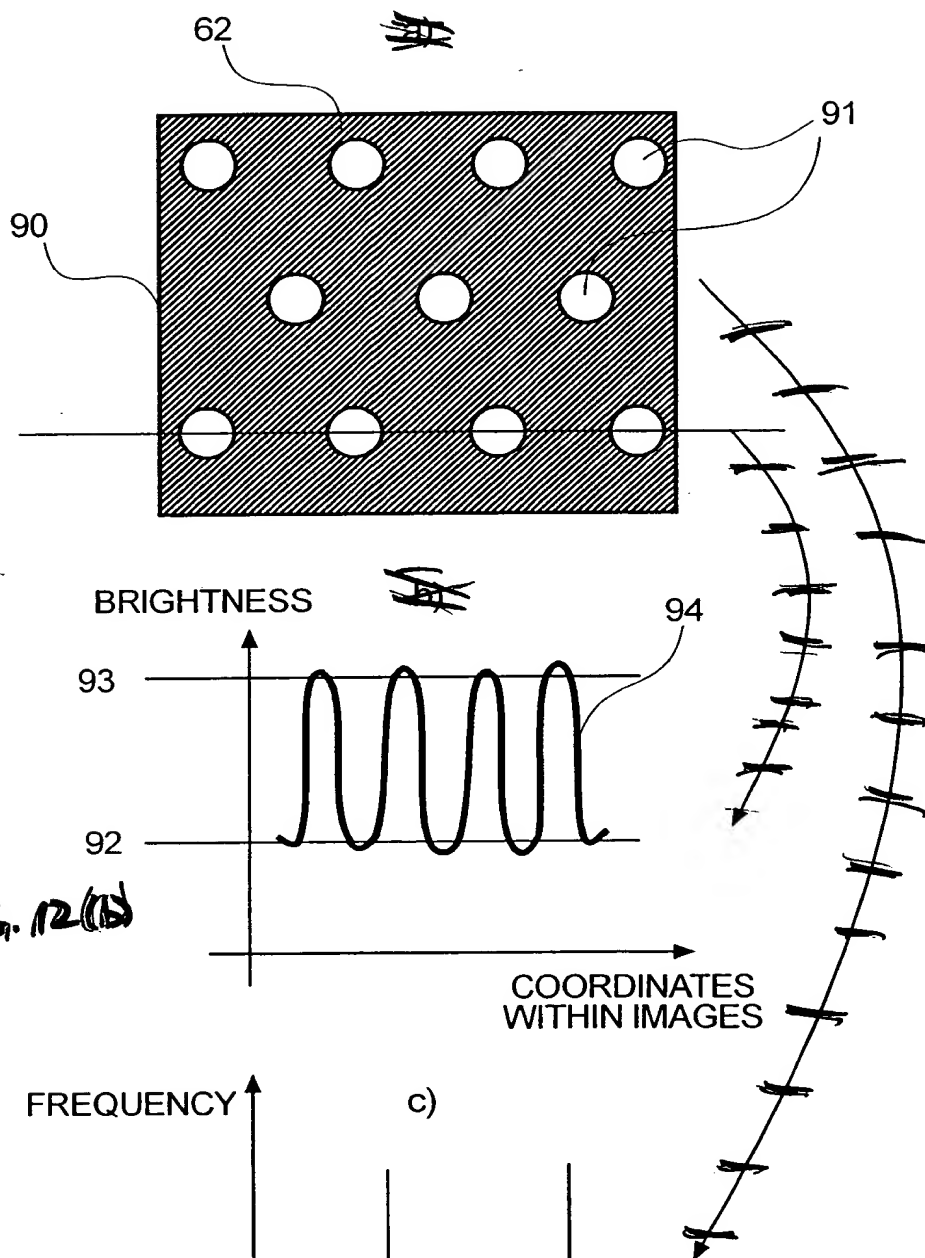


FIG. 12(b)

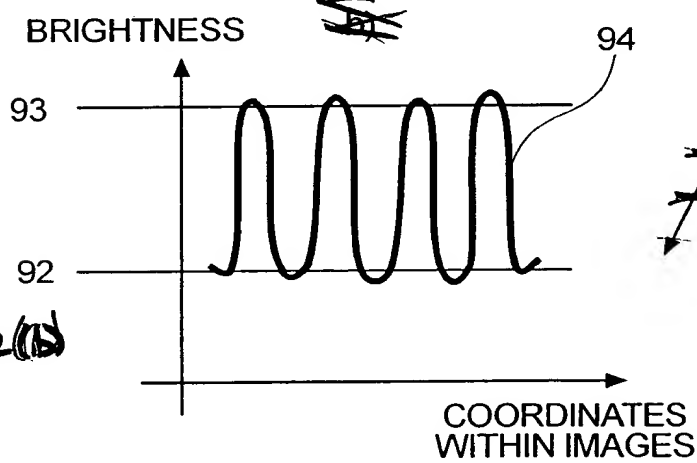


FIG. 12(c)

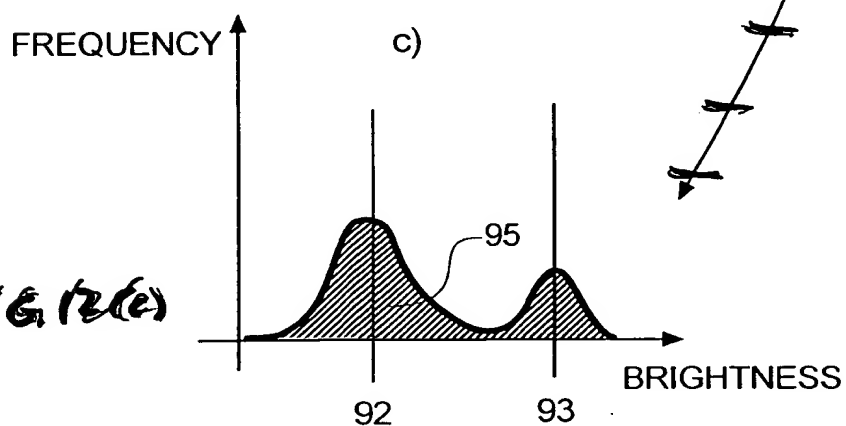


FIG. 13(a)

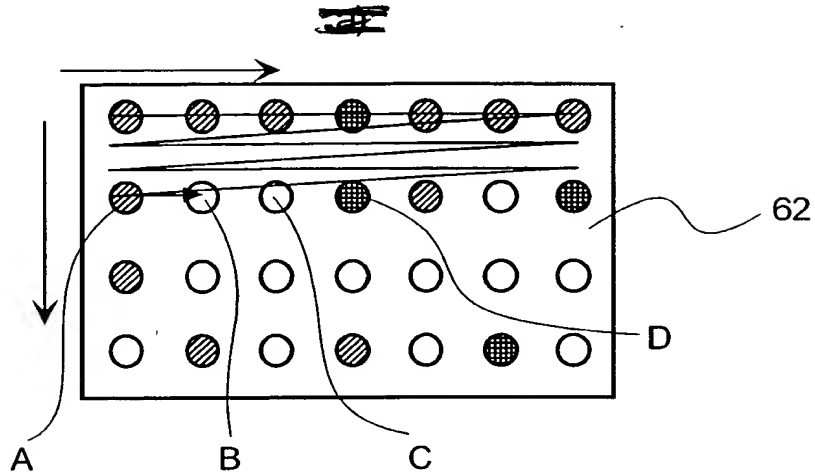


FIG. 13(b)

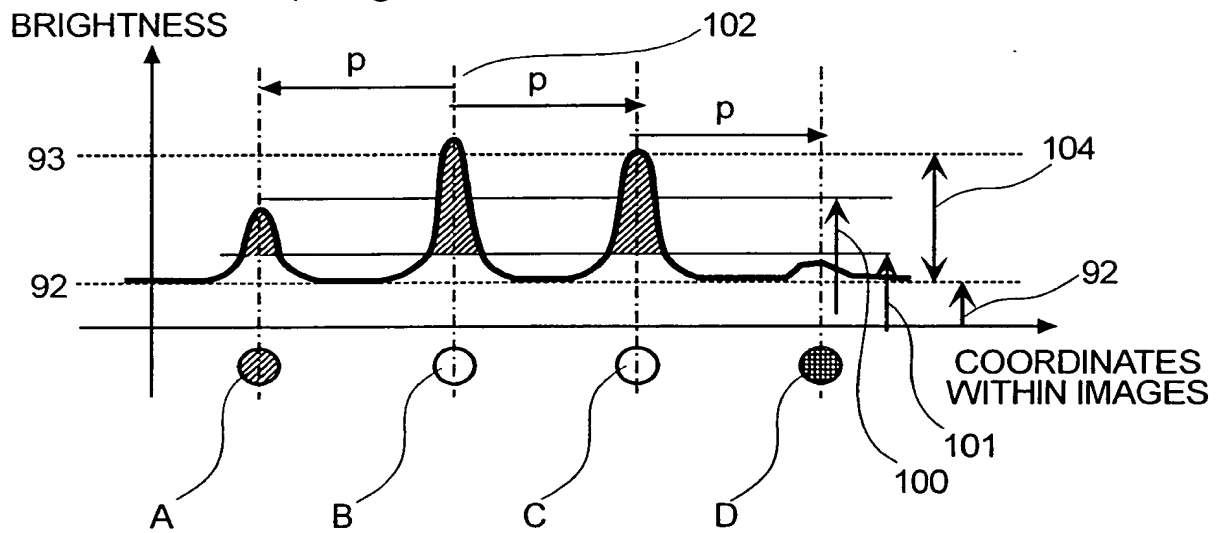
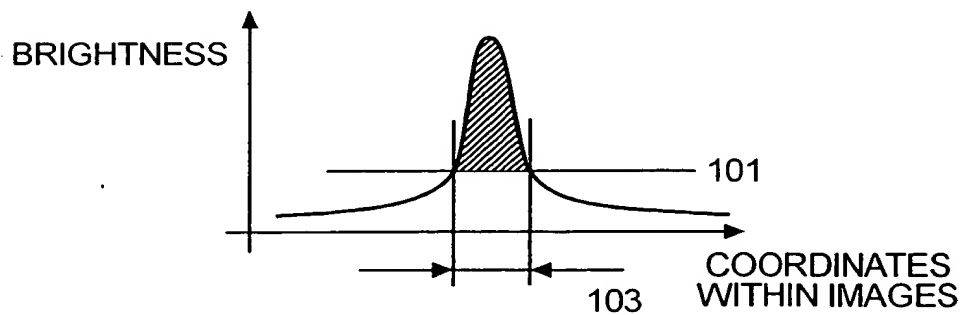


FIG. 13(c)



~~FIG. 14~~

FIG. 14(a) LOW PATTERN DENSITY

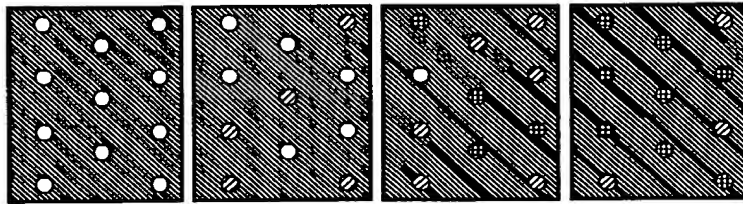
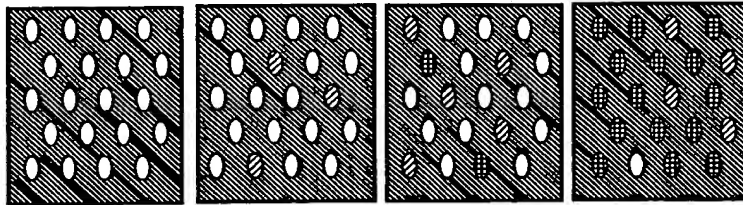


FIG. 14(b) HIGH PATTERN DENSITY



~~FIG. 15~~

FIG. 15(a)

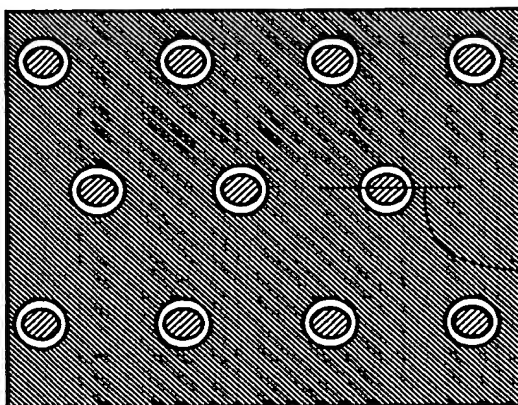
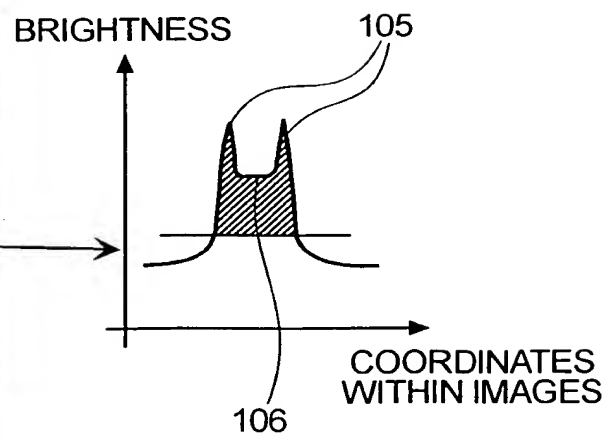


FIG. 15(b)



~~FIG. 16~~

FIG. 16(a)

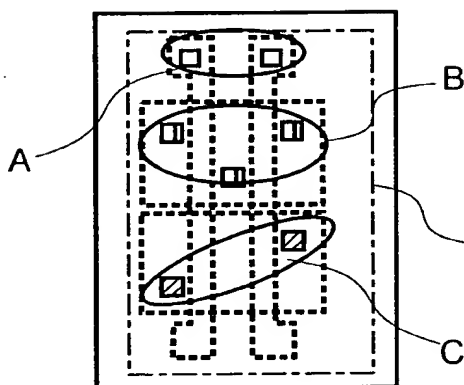


FIG. 16(b)

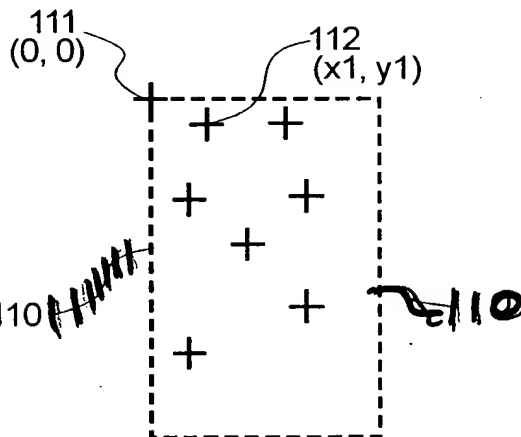
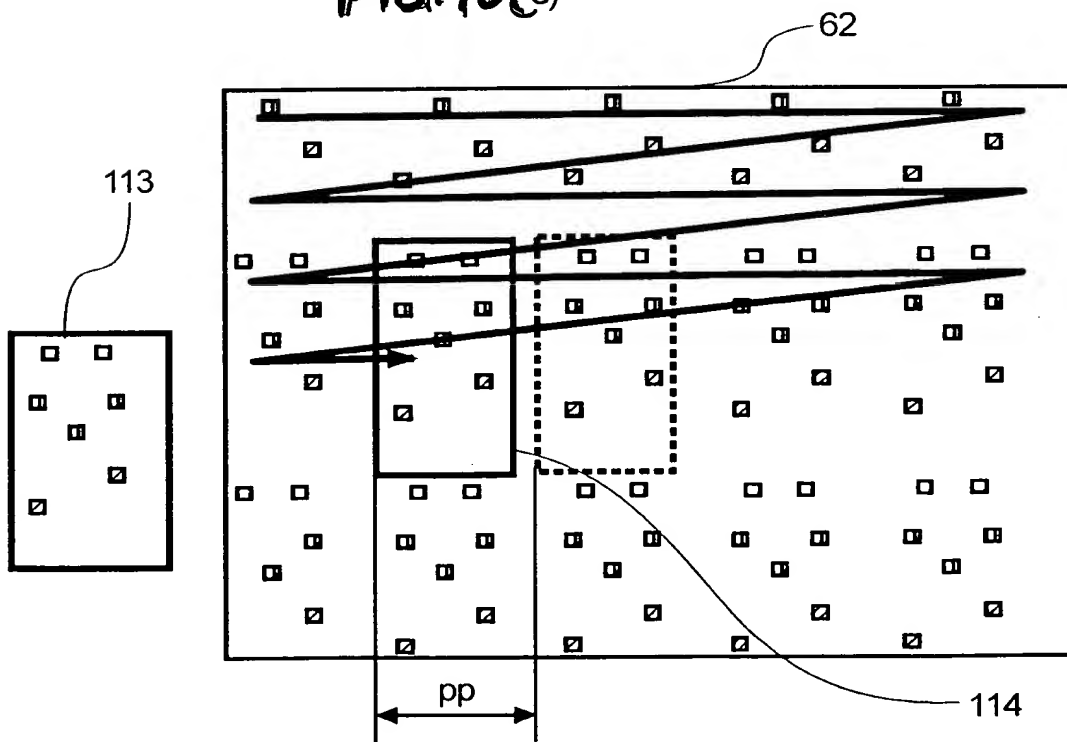


FIG. 16(c)



~~FIG. 21~~

FIG. 21 (a)

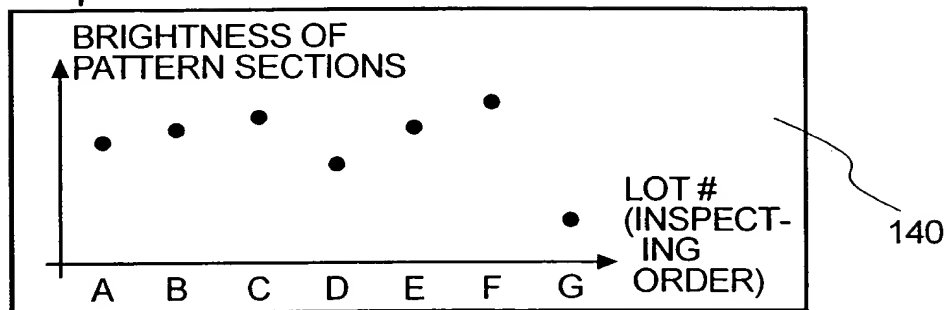


FIG. 21 (b)

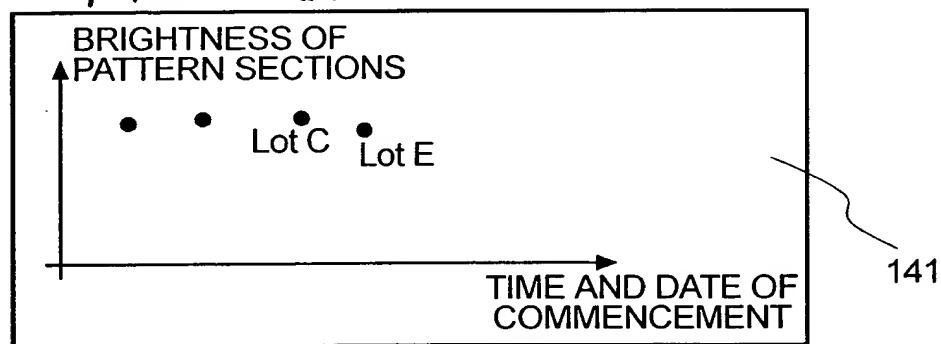


FIG. 21 (c)

